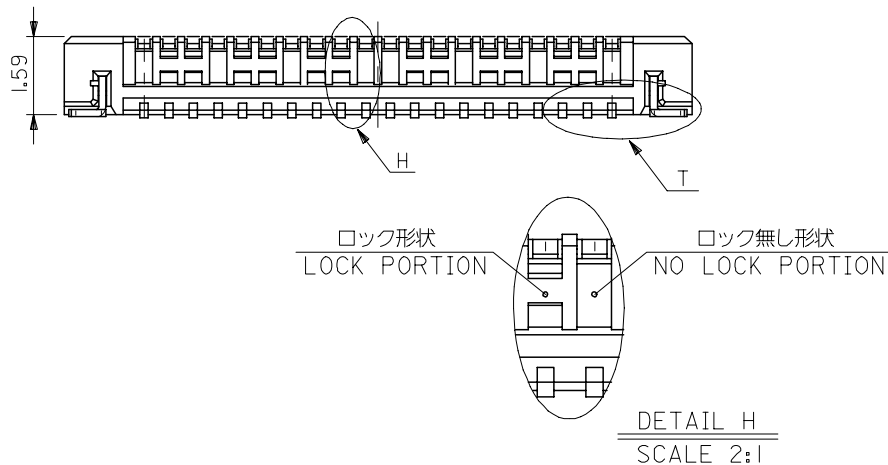
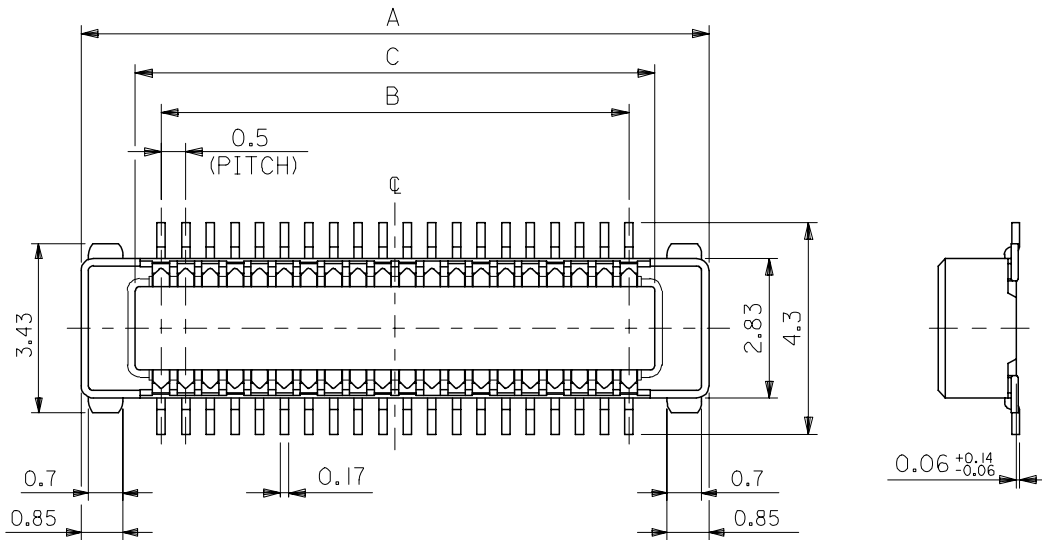


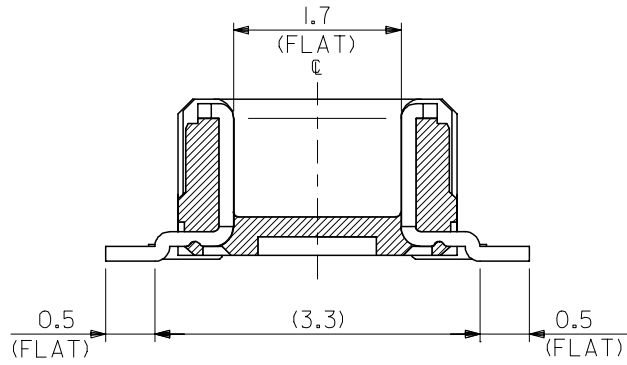
注記
NOTES:

- 材質
MATERIAL
ハウジング: LCP (液晶ポリマー)、ガラス充填、黒色、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER), GLASS FILLED, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.15)
TERMINAL: COPPER ALLOY (t=0.15)
ネイル: 銅合金 (t=0.15)
NAIL: COPPER ALLOY (t=0.15)
- メッキ仕様
PLATING
ターミナル
TERMINAL
接点部: 金メッキ 0.25マイクロメートル以上
CONTACT AREA: GOLD 0.25 MICROMETER MINIMUM
半田付け部: 金メッキ 0.35マイクロメートル以下
SOLDER TAIL AREA: GOLD 0.35 MICROMETER MAXIMUM
下地メッキ: ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5 MICROMETER MINIMUM
ネイル
NAIL
錫メッキ 1.0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1.0マイクロメートル以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM
- テール平坦度は、0.08ミリメートル以下。テールとネイルを併せた平坦度は、0.1ミリメートル以下。
TAIL COPLANARITY TO BE 0.08 MAXIMUM. TAILS AND NAILS COPLANARITY TO BE 0.1 MAXIMUM.
- 嵌合相手: 54363-****
MATED CONN.: 54363-****
- 本製品は55650-****1の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-****1

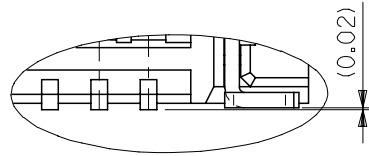


—#	28.05	27	30.25	55650-1181	110
4	18.05	17	20.25	55650-0781	70
8	15.55	14.5	17.75	55650-0681	60
12	13.05	12	15.25	55650-0581	50
20	10.55	9.5	12.75	55650-0481	40
30	8.05	7	10.25	55650-0381	30
20	5.55	4.5	7.75	55650-0281	20
ロック数 LOCKS	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

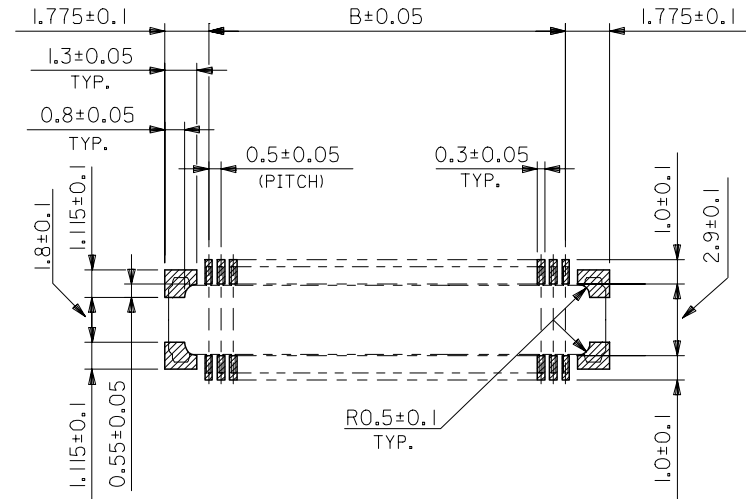
REVISED EC NO: J2008-0540 DRWN: A0YAGI 2007/09/03 CHKD: TOYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-55650-013	SHEET NO. 1 OF 2
	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



製品断面図 (半田付け部、吸着面寸法)
 DETAIL FOR SOLDERING AND VACUUM AREA



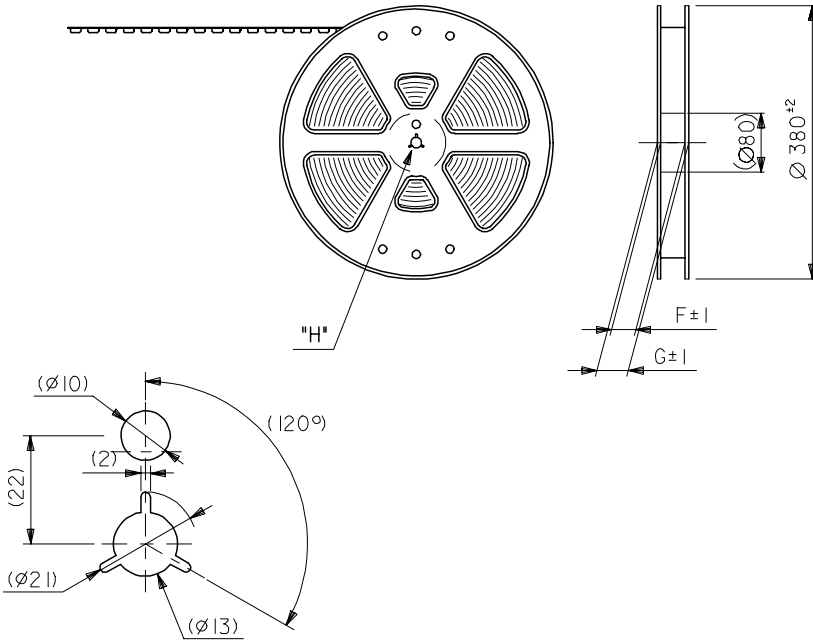
DETAIL T
 T部詳細



推奨基板寸法
 RECOMMENDED PCB PATTERN LAYOUT
 (SCALE 5:1)

REVISED EC NO: J2008-0540 DRWN: A0YAGI 2007/09/03 CHKD: TOYODA 2007/09/03 APPR: NUKITA 2007/09/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE 0.5 MM PITCH B/B CONN. PLUG NAIL ASS'Y (H=2MM) -LEAD FREE-		
	10 ^{OVER} 30 UNDER	± 0.25	CHECKED BY K. TOJO	DATE 2004/03/09	MOLEX INCORPORATED		
	30 ^{OVER}	± 0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MATERIAL NO.	DOCUMENT NO. SD-55650-013	SHEET NO. 2 OF 2
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

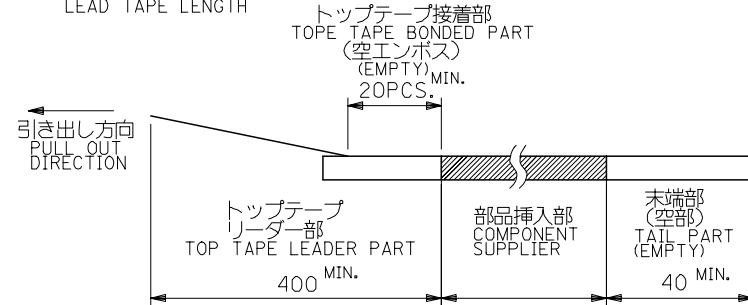
引き出し方向
PULL OUT DIRECTION



DETAIL "H"

注)
NOTES

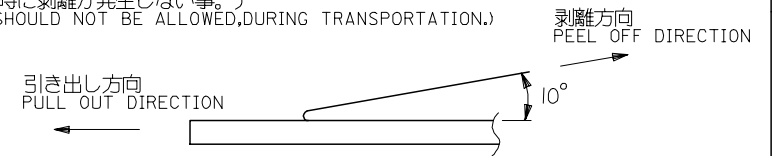
1. 製品番号 55650-***8 | 詳細寸法については、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 55650-***8 | DETAILED DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量：2500個/リール
NUMBER OF CONNECTORS:2500 PCS/REEL.
3. リードテープ長さ
LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PELLING DIRECTION AS SHOWN IN FOLLOWING FIGURE.)

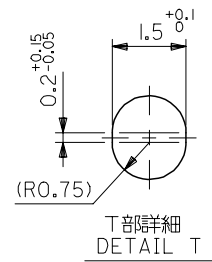
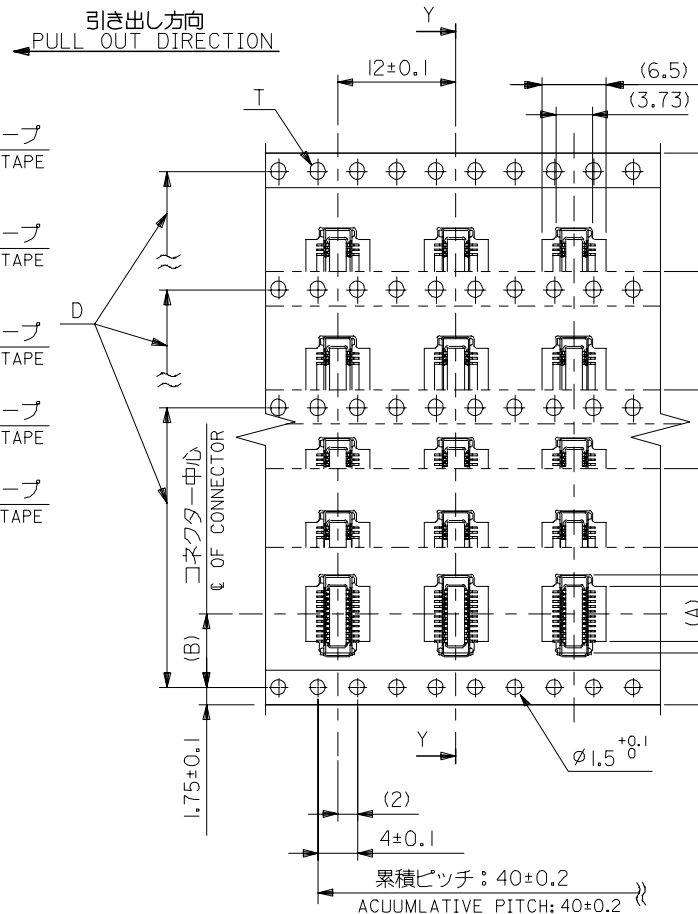
0. 1~1. 3N{ 10~130gf }

尚、本規格値は、出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しない事。)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.)



5. 材料
MATERIAL
キャリアテープ：ポリプロピレン (PP)
CARRIER TAPE: POLYPROPYLENE (PP)
トップテープ：PET, PE, PEF
TOP TAPE: PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>
REEL: POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
6. 本製品は55650-***8の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55650-***8

MATERIAL 材料	注記参照 SEE NOTES	REVISED EC NO: J2006-3588 DRW:SKATAKA 2006/05/29 CHKD:MANAKA 2006/05/30 APPR:NUKITA 2006/05/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
FINISH 仕上げ	注記参照 SEE NOTES		10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE EMBOSSD TAPE PACKAGE FOR 55650-***8 -LEAD FREE-				
WIRE RANGE 適用電線範囲	—		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	APPROVED BY M. SASAO				
INS. RANGE 被覆外径	—		30 OVER	±0.3	DATE 2004/03/09	MATERIAL NO. SEE CHART 2					
		A	ANGULAR	±3 °	DOCUMENT NO. SD-55650-014		SHEET NO. 1 OF 2				
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



49.5	45.4	44±0.3	40.4	30.45	20.2	28.05	55650-1188	110		
37.5	33.4	32±0.3	28.4	20.45	14.2	18.05	55650-0788	70		
				17.95		15.55	55650-0688	60		
29.4	25.4	24±0.3	#	15.45	11.5	13.05	55650-0588	50		
				12.95		10.55	55650-0488	40		
				10.45		8.05	55650-0388	30		
21.4	17.4	16±0.3		7.95	7.5	5.55	55650-0288	20		
G	F	E キャリアテープ幅 CARRIER TAPE WIDTH			D	(C)	(B)	(A)	製品番号 MATERIAL NO.	極数 CIRCUITS

MODEL NO. 55650-***88

MATERIAL 材料	注記参照 SEE NOTES	REVISED EC NO: J2006-3588 DRWSKATAOKA 2006/05/29 CHKD:MTANAKA 2006/05/30 APPR:NUKITA 2006/05/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
FINISH 仕上げ	注記参照 SEE NOTES		10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/09	TITLE EMBOSSD TAPE PACKAGE FOR 55650-***81 -LEAD FREE-				
WIRE RANGE 適用電線範囲	—		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/09	APPROVED BY M. SASAO				
INS. RANGE 被覆外径	—		30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/09	MOLEX INCORPORATED				
REV A			ANGULAR	±3 °	MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-55650-014		2 OF 2		
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											